

Please amend the claims as follows:

1. (Twice Amended) A semiconductor package, comprising:
a semiconductor chip provided with a plurality of input/output pads on its upper surface;
a chip paddle adjacent a bottom surface of the semiconductor chip, said chip paddle having an upper surface;
a plurality of internal leads surrounding the chip paddle wherein the upper surface of the chip paddle and at least one portion of an upper surface of the internal leads are in approximately a common plane, and wherein the chip paddle is in at least one part thicker than at least a portion of the internal leads;
conductive wires for electrically connecting the input/output pads of the semiconductor chip to the internal leads; and
a package body comprised of encapsulation material that encapsulates the semiconductor chip, the conductive wires, the chip paddle and the internal leads, wherein the chip paddle and the internal leads are externally exposed at a bottom surface of the chip paddle and the internal leads.

13. (Twice Amended) A packaged semiconductor, comprising:
a chip paddle adapted to receive a semiconductor chip, said chip paddle having an upper surface, a lower surface, and an intermediate surface positioned between and parallel to the upper surface and the lower surface;
a plurality of internal leads surrounding the chip paddle wherein the chip paddle and the leads comprise a leadframe wherein the intermediate surface of the chip paddle and at least one portion of an upper surface of the internal leads are in approximately a common plane, and wherein the chip paddle is at least one part thicker than at least a portion of the internal leads;
and

the leadframe adapted to receive a package body comprised of encapsulation material for encapsulating the chip paddle and the internal leads, wherein the chip paddle and the internal leads are externally exposed at a bottom surface of the chip paddle and the internal leads.

19. (Amended) A package for mounting a semiconductor chip, comprising:
a leadframe, the leadframe comprising;

a chip paddle wherein a surface of the chip paddle is externally exposed from the package; and

a plurality of internal leads surrounding the chip paddle, wherein a surface of each of the plurality of internal leads is externally exposed from the package;

means for receiving encapsulating material for encapsulating the leadframe;

means for locking the encapsulating means to the chip paddle;

means for providing a fluid path for the encapsulating means during encapsulation of the leadframe; and

said means for locking and said means for providing a fluid path are formed from a void caused by said chip paddle being in at least one part thicker than at least a portion of the internal leads.

25. (Amended) The package as set forth in claim 21, wherein the etched portion is located inside the package body, an upper surface of the chip paddle and a lower surface of the plurality of internal leads are in approximately a common plane, the chip paddle is bonded to a bottom surface of a semiconductor chip and at least one of the plurality of internal leads has an etched part at an end facing the chip paddle.